

**QUICK TURN
 MANUFACTURING CAPABILITIES**

Standard products

Min. conductor width (1 oz copper, inner layer)	0.006
Min. conductor space (1 oz copper, inner layer)	0.006
Min. conductor width (1/2 oz copper, inner layer)	0.004
Min. conductor space (1/2 oz copper, inner layer)	0.004
Min. conductor width/space (outer layer)	0.006/0.006
Min. electrical test pitch	0.010
Minimum mech drilled via (thickness dependent)	0.0135
Fab Allowance (Pad size = drill + 2AR + FA) (more than 12 layers add 0.002)	0.015
Max. drilled hole aspect ratio	7 to 1
Max. overall board thickness	0.25
Min. tolerance on PTHs	+/- 0.003
Min. tolerance on NPTHs	+/-0.002
True Positional Tolerance (Rigid sections)	R.T.P. 0.008"
Avg layer count (rigid sections)	8 to 20
Avg layer count (flex sections)	8 to 18
Min. distance of feature to edge	0.015
Min. Flexible dielectric thickness (design dep't.)	0.002
Min. base copper thicknesses	1/2 ounce
Max. panel size	18 x 24
Impedance tolerance (characteristic, design dep't)	+/- 10%
Impedance tolerance (differential, design dep't)	+/- 15%
Warpage (design dependent)	1.50%
Surface finishes	HAL, tin/lead reflow, Gold/Nickel (electrolytic, ENIG)
Dielectric materials	FR4 (high Tg), Kapton, GI Polyimide
Flexible constructions	Regal 1, Adhesiveless (AP and "true"), Types 1-5
Soldermask types	Dry film, LPISM
Conformal coatings	Acrylic, urethane, parylene
Assembly capabilities	ANSI-J/STD 001, thru-hole, SMT